

FDD6296/FDU6296

30V N-Channel Fast Switching PowerTrench[®] MOSFET

General Description

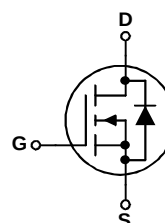
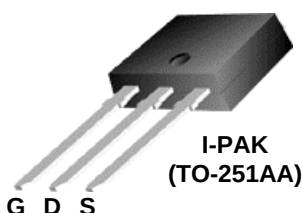
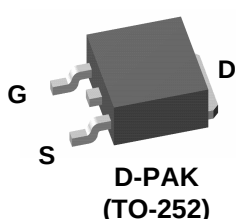
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $R_{DS(ON)}$ and fast switching speed.

Applications

- DC/DC converter
- Power management

Features

- 50A, 30 V $R_{DS(ON)} = 8.8 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$
 $R_{DS(ON)} = 11.3 \text{ m}\Omega @ V_{GS} = 4.5 \text{ V}$
- Low gate charge
- Fast switching
- High performance trench technology for extremely low $R_{DS(ON)}$



Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 20	
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$ (Note 3)	50	A
	@ $T_A = 25^\circ\text{C}$ (Note 1a)	15	
	Pulsed (Note 1a)	100	
P_D	Power Dissipation @ $T_C = 25^\circ\text{C}$ (Note 3)	52	W
	@ $T_A = 25^\circ\text{C}$ (Note 1a)	3.8	
	@ $T_A = 25^\circ\text{C}$ (Note 1b)	1.6	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	2.9	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	40	
	Thermal Resistance, Junction-to-Ambient (Note 1b)	96	

Package Marking and Ordering Information

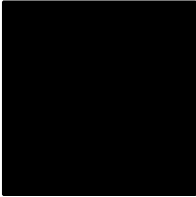
Device Marking	Device	Package	Reel Size	Tape width	Quantity
FDD6296	FDD6296	D-PAK (TO-252)	13"	12mm	2500 units
FDU6296	FDU6296	I-PAK (TO-251)	Tube	N/A	75

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Drain-Source Avalanche Ratings (Note 2)						
E _{AS}	Drain-Source Avalanche Energy	Single Pulse, V _{DD} = 15 V, I _D =15A			165	mJ
I _{AS}	Drain-Source Avalanche Current				15	A
Off Characteristics						
BV _{DSS}	Drain–Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		29		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μA
I _{GSS}	Gate–Body Leakage	V _{GS} =± 20 V, V _{DS} = 0 V			± 100	nA
On Characteristics (Note 2)						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	1	1.7	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		–0.5		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	V _{GS} = 10 V, I _D = 15 A V _{GS} = 4.5 V, I _D = 13 A V _{GS} = 10 V, I _D = 15 A, T _J =125°C		7.5 9.0 9.3	8.8 11.3 15.0	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 15 A		58		S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 15 V, V _{GS} = 0 V, f = 1.0 MHz		1440		pF
C _{oss}	Output Capacitance			400		pF
C _{rss}	Reverse Transfer Capacitance			140		pF
R _G	Gate Resistance	V _{GS} = 15 mV, f = 1.0 MHz		1.3		Ω
Switching Characteristics (Note 2)						
t _{d(on)}	Turn–On Delay Time	V _{DD} = 15 V, I _D = 1 A, V _{GS} = 10 V, R _{GEN} = 6 Ω		11	19	ns
t _r	Turn–On Rise Time			6	11	ns
t _{d(off)}	Turn–Off Delay Time			29	46	ns
t _f	Turn–Off Fall Time			13	23	ns
Q _g	Total Gate Charge	V _{DS} = 15V, I _D = 15 A, V _{GS} = 10 V		22.5	31.5	nC
Q _g	Total Gate Charge	V _{DS} = 15V, I _D = 15 A, V _{GS} = 5 V		12.2	17	nC
Q _{gs}	Gate–Source Charge			4		nC
Q _{gd}	Gate–Drain Charge			3.5		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain–Source Diode Forward Current				3.2	A
V _{SD}	Drain–Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 3.2 A (Note 2)		0.74	1.2	V
t _{rr}	Diode Reverse Recovery Time	I _F = 15 A,		25		nS
Q _{rr}	Diode Reverse Recovery Charge	d _I F/d _t = 100 A/μs		13		nC

Electrical Characteristics (cont'd)

- Notes:**
- $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) $R_{\theta JA} = 40^{\circ}\text{C/W}$ when mounted on a 1in² pad of 2 oz copper



b) $R_{\theta JA} = 96^{\circ}\text{C/W}$ when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

- Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%
- Maximum current is calculated as:
$$\sqrt{\frac{P_D}{R_{DS(on)}}}$$
 where P_D is maximum power dissipation at $T_C = 25^{\circ}\text{C}$ and $R_{DS(on)}$ is at $T_{J(max)}$ and $V_{GS} = 10\text{V}$. Package current limitation is 21A

Typical Characteristics

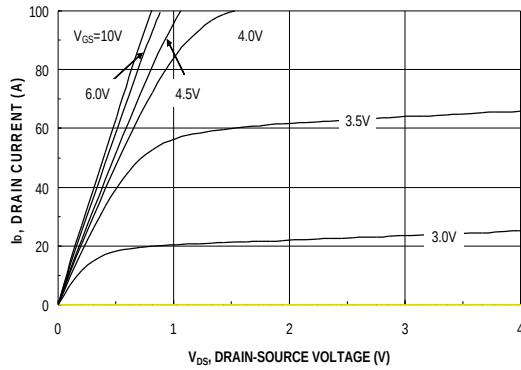


Figure 1. On-Region Characteristics

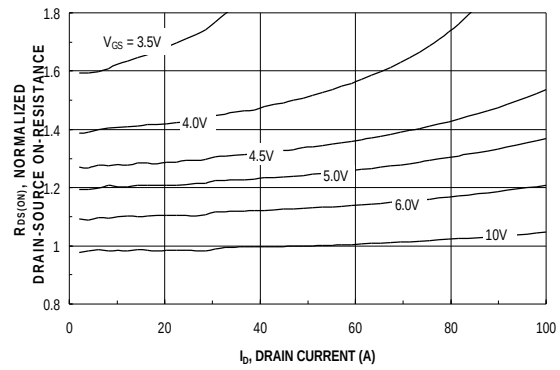


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

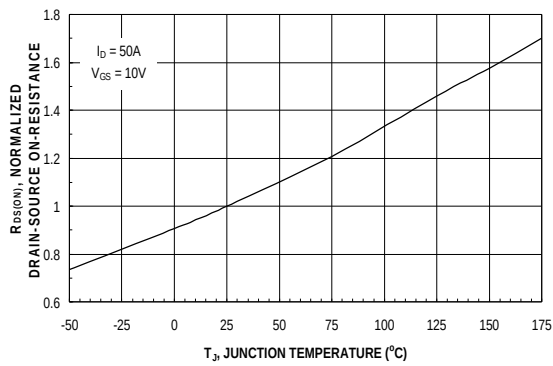


Figure 3. On-Resistance Variation with Temperature

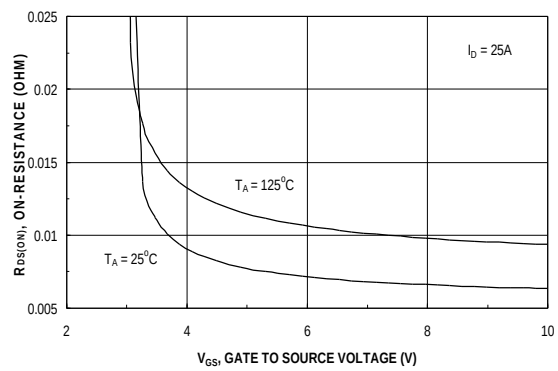


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

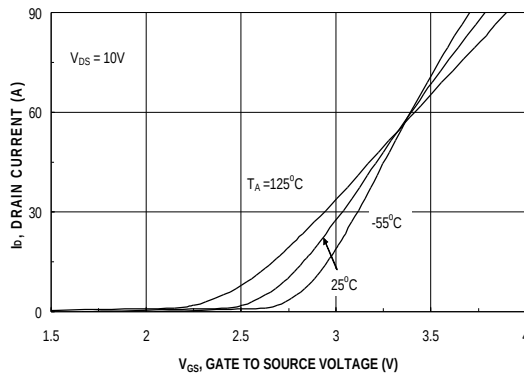


Figure 5. Transfer Characteristics

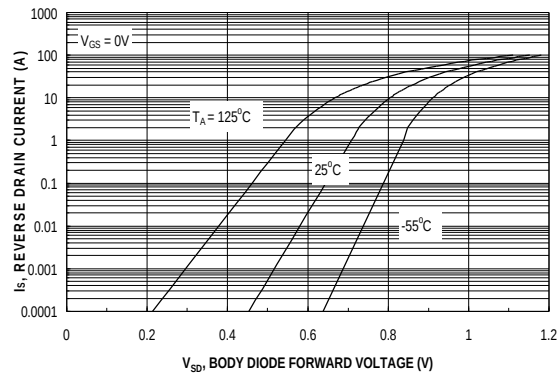


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Characteristics

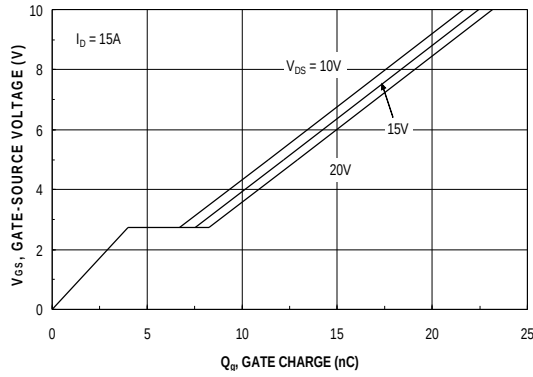


Figure 7. Gate Charge Characteristics

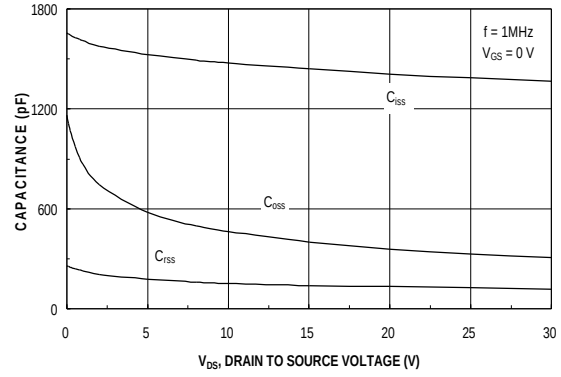


Figure 8. Capacitance Characteristics

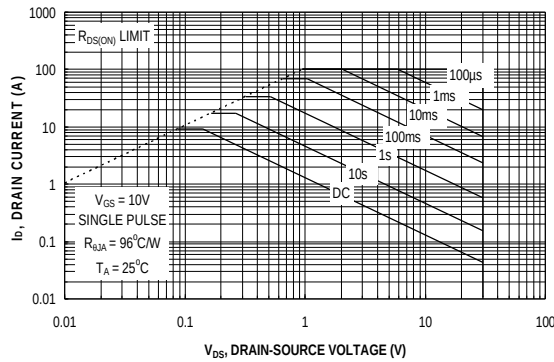


Figure 9. Maximum Safe Operating Area

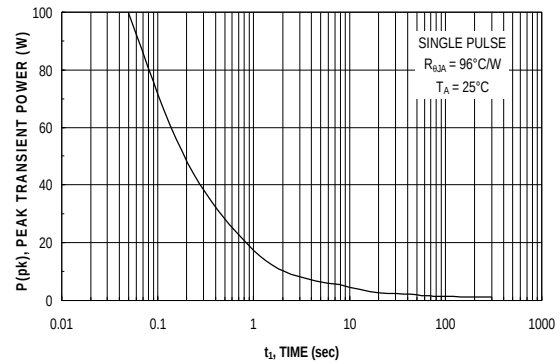


Figure 10. Single Pulse Maximum Power Dissipation

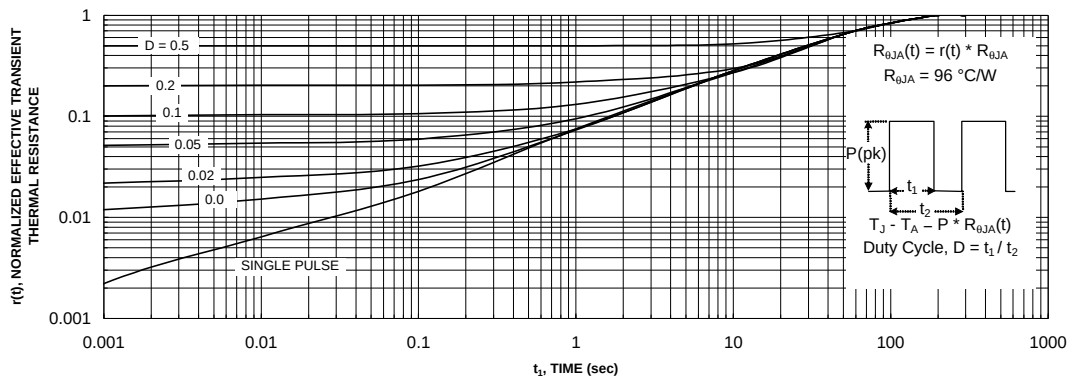


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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FACT™	ImpliedDisconnect™	OCXPro™	μSerDes™	UltraFET®
FACT Quiet Series™		OPTOLOGIC®	SILENT SWITCHER®	VCX™
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